

Product / Package Information

Package	TQFP
Body Size (mm)	7 X 7 X 1.0
Lead Count	32
Terminal Finish	NiPdAu
MS Number	MS012094B

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes
Last Updated	16-Apr-19

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.23E-01	87.00	870000	42.87	428701
Thermosets	Epoxy Resin	Proprietary	1.06E-02	7.50	75000	3.70	36957
Thermosets	Phenol Resin	Proprietary	7.05E-03	5.00	50000	2.46	24638
Other inorganic materials	Carbon black	1333-86-4	7.05E-04	0.50	5000	0.25	2464
Subtotal			1.41 E-01	100.00	1000000	49.28	492760

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.01E-01	97.50	975000	35.14	351405
Copper & its alloys	Iron	7439-89-6	2.42E-03	2.35	23500	0.85	8470
Copper & its alloys	Zinc	7440-66-6	1.24E-04	0.12	1200	0.04	432
Copper & its alloys	Phosphorus	7723-14-0	3.09E-05	0.03	300	0.01	108
Subtotal			1.03 E-01	100.00	1000000	36.04	360415

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	4.48 E-03	88.26	882600	1.57	15669
Precious Metals	Palladium	7440-05-3	2.66 E-04	5.24	52400	0.09	930
Precious Metals	Gold	7440-57-5	3.30 E-04	6.50	65000	0.12	1154
Subtotal			5.08E-03	100.0	1000000	1.78	17753

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious Metals	Gold	7440-57-5	4.87E-03	99.0	990000	1.70	17024
Precious Metals	Palladium	7440-05-3	4.92E-05	1.00	10000	0.02	172
Subtotal			4.92E-03	100.00	1000000	1.72	17196

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.78E-02	100.0	1000000	9.73	97257

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.51E-03	60	600000	0.88	8772
Other inorganic materials	Silica	Trade secret	4.18E-04	10	100000	0.15	1462
Other inorganic materials	Allyl compound	Trade secret	3.14E-04	7.5	75000	0.11	1096
Other organic materials	Epoxy resin A	9003-36-5	1.05E-04	2.5	25000	0.04	365
Other organic materials	Epoxy resin B	Trade secret	1.46E-04	3.5	35000	0.05	512
Other organic materials	Diluent A	Trade secret	1.05E-04	2.5	25000	0.04	365
Other organic materials	Diluent B	Trade secret	1.46E-04	3.5	35000	0.05	512
Other organic materials	Hardener	Trade secret	1.46E-04	3.5	35000	0.05	512
Other organic materials	Dicyandiamide	461-58-5	1.46E-04	3.5	35000	0.05	512
Other organic materials	Organic peroxide	Trade secret	1.46E-04	3.5	35000	0.05	512
Subtotal	Subtotal		4.18 E-03	100.00	1000000	1.46	14620

Package Totals			Weight (g)	Percentage (%)	PPM
			2.86 E-01	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



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